# **High Current Surface Mount** PNP Silicon Low V<sub>CE-SAT</sub> Switching Transistor for **Load Management in Portable Applications**

• This is a Pb-Free Device

# **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-35	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-55	Vdc
Emitter-Base Voltage	$V_{EBO}$	-5.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	-2.0	Adc
Collector Current – Peak	I <sub>CM</sub>	-7.0	Α
Electrostatic Discharge	ESD	HBM Cla	

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T <sub>A</sub> = 25°C	P <sub>D</sub> (Note 1)	635	mW
Derate above 25°C		5.1	mW/°C
Thermal Resistance, Junction–to–Ambient	R <sub>θJA</sub> (Note 1)	200	°C/W
Total Device Dissipation $T_A = 25^{\circ}C$	P <sub>D</sub> (Note 2)	1.35	W
Derate above 25°C		11	mW/°C
Thermal Resistance, Junction–to–Ambient	R <sub>θJA</sub> (Note 2)	90	°C/W
Thermal Resistance, Junction–to–Lead #1	$R_{ heta JL}$	15	°C/W
Total Device Dissipation (Single Pulse < 10 sec)	P <sub>Dsingle</sub> (Notes 2 & 3)	2.75	W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- FR-4 @ 100 mm<sup>2</sup>, 1 oz copper traces.
   FR-4 @ 500 mm<sup>2</sup>, 1 oz copper traces.
- 3. Thermal response.

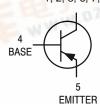


# ON Semiconductor®

http://onsemi.com

# 35 VOLTS **2.0 AMPS** PNP TRANSISTOR

COLLECTOR 1, 2, 3, 6, 7, 8





ChipFET™ **CASE 1206A** STYLE 4

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E 5	4 B	4 [	.15	] 5

G4 = Specific Device Code M = Month Code

# ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NSS35200CF8T1G	ChipFET (Pb-Free)	3000/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25$ °C unless otherwise noted)

Characteristic	Symbol	Min	Typical	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I <sub>C</sub> = –10 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-35	-45	_	Vdc
Collector – Base Breakdown Voltage (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-55	-65	_	Vdc
Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	-5.0	-7.0	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = -35 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-0.03	-0.1	μAdc
Collector–Emitter Cutoff Current (V <sub>CES</sub> = -35 Vdc)	I <sub>CES</sub>	_	-0.03	-0.1	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = -6.0 Vdc)	I <sub>EBO</sub>	-	-0.01	-0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 4) ( $I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}$ ) ( $I_C = -1.5 \text{ A}, V_{CE} = -2.0 \text{ V}$ ) ( $I_C = -2.0 \text{ A}, V_{CE} = -2.0 \text{ V}$ )	h <sub>FE</sub>	100 100 100	200 200 200	- 400 -	
Collector – Emitter Saturation Voltage (Note 4) ( $I_C = -0.1 \text{ A}$ , $I_B = -0.010 \text{ A}$ ) ( $I_C = -1.0 \text{ A}$ , $I_B = -0.010 \text{ A}$ ) ( $I_C = -2.0 \text{ A}$ , $I_B = -0.02 \text{ A}$ )	V <sub>CE(sat)</sub>	- - -	- - -	-0.10 -0.15 -0.30	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = -1.0 \text{ A}, I_B = -0.01 \text{ A})$	V <sub>BE(sat)</sub>	-	-0.68	-0.85	V
Base – Emitter Turn–on Voltage (Note 4) $(I_C = -2.0 \text{ A}, V_{CE} = -3.0 \text{ V})$	V <sub>BE(on)</sub>	_	-0.81	-0.875	V
Cutoff Frequency ( $I_C = -100 \text{ mA}$ , $V_{CE} = -5.0 \text{ V}$ , $f = 100 \text{ MHz}$ )	f <sub>T</sub>	100	-	-	MHz
Input Capacitance (V <sub>EB</sub> = -0.5 V, f = 1.0 MHz)	Cibo	-	600	650	pF
Output Capacitance (V <sub>CB</sub> = -3.0 V, f = 1.0 MHz)	Cobo	-	85	100	pF
Turn–on Time ( $V_{CC}$ = –10 V, $I_{B1}$ = –100 mA, $I_{C}$ = –1 A, $R_{L}$ = 3 $\Omega$ )	t <sub>on</sub>	-	35	-	nS
Turn–off Time ( $V_{CC}$ = -10 V, $I_{B1}$ = $I_{B2}$ = -100 mA, $I_{C}$ = 1 A, $R_{L}$ = 3 $\Omega$ )	t <sub>off</sub>	-	225	-	nS

Turn-off Time ( $V_{CC} = -10 \text{ V}$ ,  $I_{B1} = I_{B2} = -100 \text{ mA}$ ,  $I_C = 1 \text{ A}$ ,  $R_L = -100 \text{ mA}$ ,  $I_C = 1 \text{ A}$ ,

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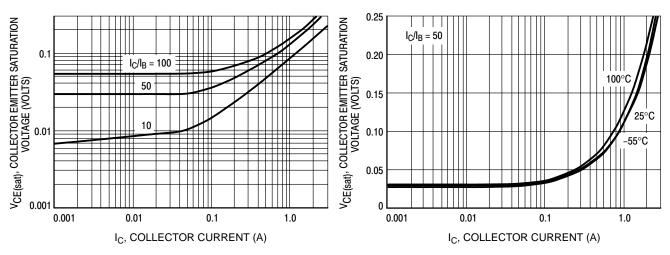


Figure 1. Collector Emitter Saturation Voltage versus Collector Current

Figure 2. Collector Emitter Saturation Voltage versus Collector Current

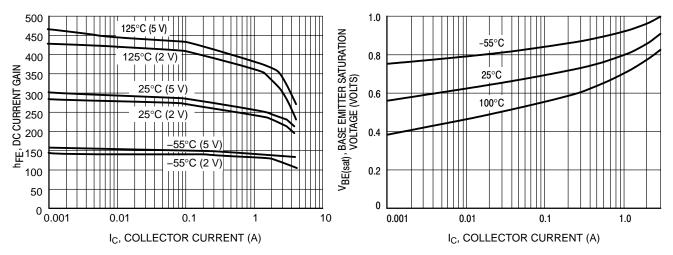


Figure 3. DC Current Gain versus Collector Current

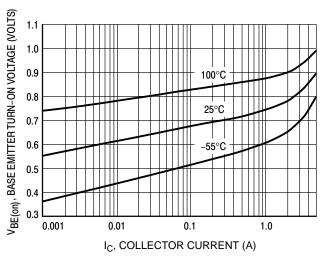


Figure 5. Base Emitter Turn-On Voltage versus Collector Current

Figure 4. Base Emitter Saturation Voltage versus Collector Current

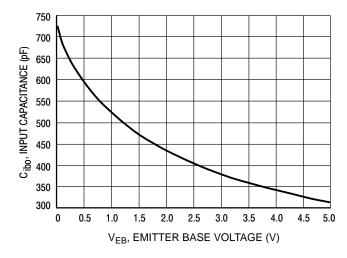


Figure 6. Input Capacitance

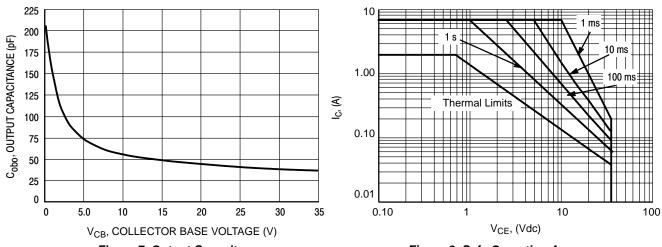


Figure 7. Output Capacitance Figure 8. Safe Operating Area

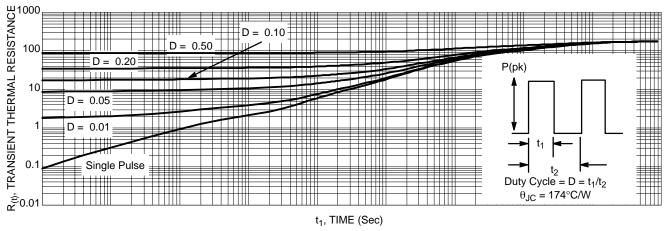
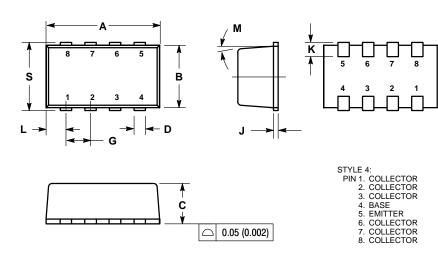


Figure 9. Normalized Thermal Response

#### PACKAGE DIMENSIONS

# ChipFET CASE 1206A-03 **ISSUE PRELIMINARY**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. MOLD GATE BURRS SHALL NOT EXCEED 0.13 MM PER SIDE.
- O.13 MM PER SIDE.

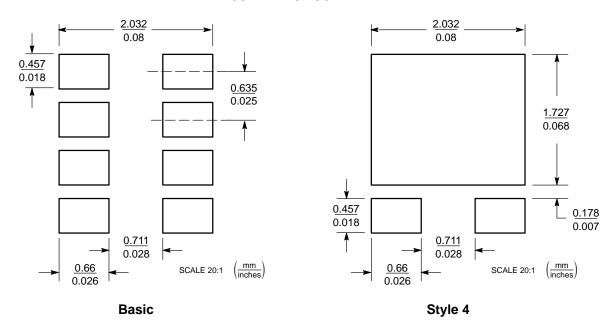
  LEADFRAME TO MOLDED BODY OFFSET IN HORIZONTAL AND VERTICAL SHALL NOT EXCEED 0.08 MM.

  DIMENSIONS A AND B EXCLUSIVE OF MOLD GATE BURRS.

  NO MOLD FLASH ALLOWED ON THE TOP AND BOTTOM LEAD SURFACE.

	MILLIMETERS		INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	2.95	3.10	0.116	0.122		
В	1.55	1.70	0.061	0.067		
C	1.00	1.10	0.039	0.043		
D	0.25	0.35	0.010	0.014		
G	0.65 BSC		0.02	0.025 BSC		
J	0.10	0.20	0.004	0.008		
K	0.28	0.42	0.011	0.017		
L	0.55 BSC		0.022 BSC			
М	5° 1	MOV	5° NOM			
S	1.80	2.00	0.072	0.080		

#### **SOLDERING FOOTPRINT\***



<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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